

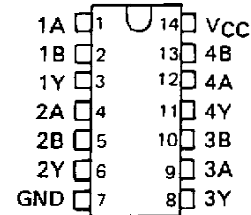
SDLS034

# QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS

SN5409, SN54LS09, SN54S09,  
SN7409, SN74LS09, SN74S09  
DECEMBER 1983—REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

SN5409, SN54LS09, SN54S09 . . . J OR W PACKAGE  
SN7409 . . . N PACKAGE  
SN74LS09, SN74S09 . . . D OR N PACKAGE  
(TOP VIEW)

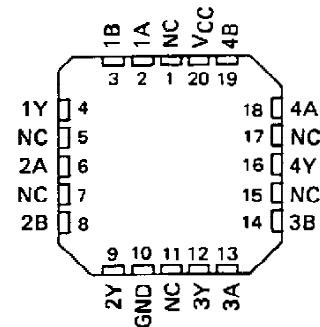


### description

These devices contain four independent 2-input AND gates. The open-collector outputs require pull-up resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher  $V_{OH}$  levels.

The SN5409, SN54LS09, and SN54S09 are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN7409, SN74LS09, and SN74S09 are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54LS09, SN54S09 . . . FK PACKAGE  
(TOP VIEW)

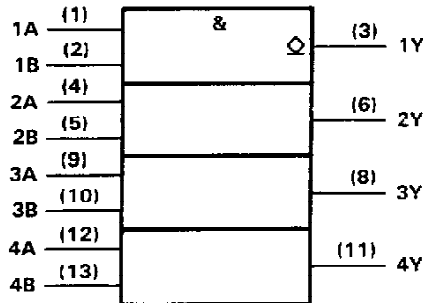


FUNCTION TABLE (each gate)

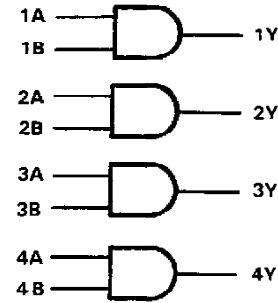
INPUTS		OUTPUT
A	B	Y
H	H	H
L	X	L
X	L	L

NC—No internal connection

### logic symbol



### logic diagram (positive logic)



$$Y = A \cdot B \text{ or } Y = \overline{\overline{A} + \overline{B}}$$

† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

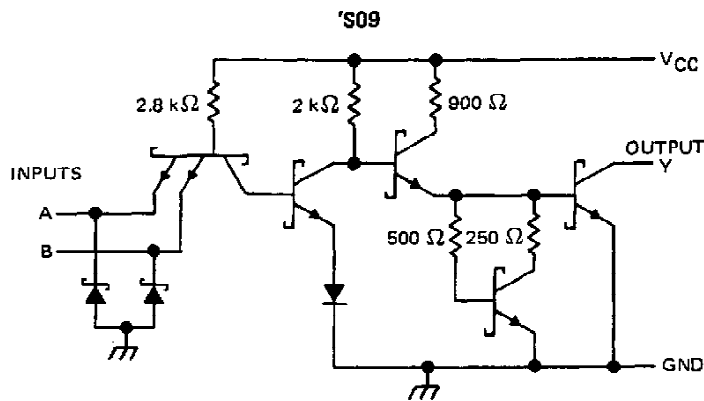
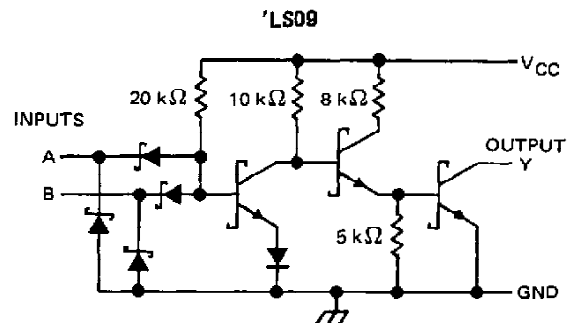
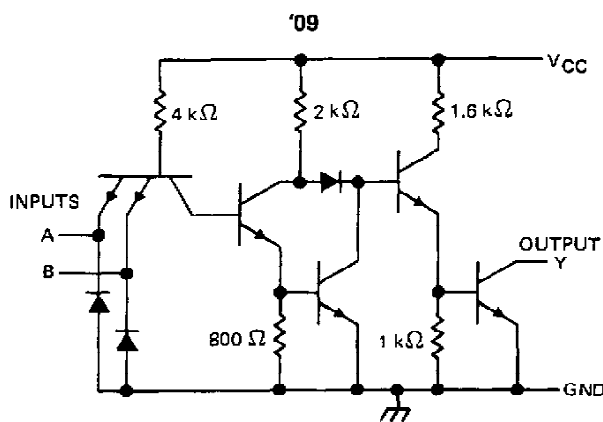
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

  
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**SN5409, SN54LS09, SN54S09,  
SN7409, SN74LS09, SN74S09  
QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS**

schematics (each gate)



Resistor values shown are nominal.

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)**

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Input voltage: '09, 'S09	5.5 V
'LS09	7 V
Off-state output voltage	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

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**SN5409, SN7409**  
**QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS**

**recommended operating conditions**

	SN5409			SN7409			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$ Supply voltage	4.5	5	5.5	4.75	5	5.25	V
$V_{IH}$ High-level input voltage	2			2			V
$V_{IL}$ Low-level input voltage			0.8			0.8	V
$V_{OH}$ High-level output voltage			5.5			5.5	V
$I_{OL}$ Low-level output current			16			16	mA
$T_A$ Operating free-air temperature	-55		125	0		70	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT
$V_{IK}$	$V_{CC} = \text{MIN}$ , $I_I = -12 \text{ mA}$		-1.5		V
$I_{OH}$	$V_{CC} = \text{MIN}$ , $V_{IH} = 2 \text{ V}$ , $V_{OH} = 5.5 \text{ V}$		0.25		mA
$V_{OL}$	$V_{CC} = \text{MIN}$ , $V_{IL} = 0.8 \text{ V}$ , $I_{OL} = 16 \text{ mA}$	0.2	0.4		V
$I_I$	$V_{CC} = \text{MAX}$ , $V_I = 5.5 \text{ V}$		1		mA
$I_{IH}$	$V_{CC} = \text{MAX}$ , $V_I = 2.4 \text{ V}$		40		μA
$I_{IL}$	$V_{CC} = \text{MAX}$ , $V_I = 0.4 \text{ V}$		-1.6		mA
$I_{CCH}$	$V_{CC} = \text{MAX}$ , $V_I = 4.5 \text{ V}$		11	21	mA
$I_{CCL}$	$V_{CC} = \text{MAX}$ , $V_I = 0 \text{ V}$		20	33	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

**switching characteristics,  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^\circ\text{C}$  (see note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{PLH}$	A or B	Y	$R_L = 400 \Omega$ , $C_L = 15 \text{ pF}$		21	32	ns
$t_{PHL}$					16	24	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



# SN54LS09, SN74LS09 QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS

## recommended operating conditions

	SN54LS09			SN74LS09			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.7			0.8	V
V <sub>OH</sub> High-level output voltage			5.5			5.5	V
I <sub>OL</sub> Low-level output current			4			8	mA
T <sub>A</sub> Operating free-air temperature	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS09			SN74LS09			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA			-1.5			-1.5	V
I <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>OH</sub> = 5.5 V			0.1			0.1	mA
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	V
	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, I <sub>OL</sub> = 8 mA					0.35	0.5	
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V			0.1			0.1	mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			20			20	μA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-0.4			-0.4	mA
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V		2.4	4.8		2.4	4.8	mA
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V		4.4	8.8		4.4	8.8	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

## switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A or B	Y	R <sub>L</sub> = 2 kΩ, C <sub>L</sub> = 15 pF		20	35	ns
t <sub>PHL</sub>					17	35	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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**SN54S09, SN74S09**  
**QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS**

**recommended operating conditions**

	SN54S09			SN74S09			UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX			
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V		
V <sub>IH</sub> High-level input voltage	2			2			V		
V <sub>IL</sub> Low-level input voltage	0.8			0.8			V		
V <sub>OH</sub> High-level output voltage	5.5			5.5			V		
I <sub>OL</sub> Low-level output current	20			20			mA		
T <sub>A</sub> Operating free-air temperature	- 55			125			0	70	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = - 18 mA			- 1.2	V	
I <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>OH</sub> = 5.5 V			0.25	mA	
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 20 mA			0.5	V	
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1	mA	
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			50	μA	
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V			- 2	mA	
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V			18	32	mA
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V			32	57	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

**switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A or B	Y	R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 15 pF	6.5	10	ns	
t <sub>PHL</sub>				6.5	10	ns	
t <sub>PLH</sub>			R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 50 pF	9	ns		
t <sub>PHL</sub>				9	ns		

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
80019012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8001901CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
8001901CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
8001901DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
8001901DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7409N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7409N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS09D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS09J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS09N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS09N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LS09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74S09NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS09DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS09NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S09DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74S09NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS09DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS09NSR	SO	NS	14	2000	346.0	346.0	33.0
SN74S09DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74S09NSR	SO	NS	14	2000	346.0	346.0	33.0

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AB.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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